



CQHS350 Reliability Test results

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OS Design DEPT.

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No.	Test Item	Testing conditions	Conditions of acceptability	Number of samples	Number of failures
1	Heat cycle test	(1) -40℃~125℃ 30minutes each (2) 600cycles	(1)No degradation of electric characteristics after test.	5	0
2	High temperature/ High humidity bias test	(1) Ta=85℃,RH=85% (2) At rated input (3) Load 0% (4) 1000hours	(1)No degradation of electric characteristics after test.	5	0
3	Vibration test	(1) $f=10\sim55\text{Hz}$, 49.0m/s^2 (5G) (2) 3minutes period (3) 1hour each X,Y and Z axis	(1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No marked damage of appearance.	3	0
4	Impact test	(1) 196.1m/s^2 (20G),11ms (2) Once each X,Y and Z axis	(1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No marked damage of appearance.	3	0
5	Soldering heat test	(1) 260℃,15seconds (2) Mounting board : $t=1.6\text{mm}$ / FR-4	(1)No crack at solder joint. (2)No marked damage of appearance.	1	0
6	Soldering test	(1) Pre-process Vapor agein(100℃/100%),1H Flux treatment (2) Soldering $235^\circ\text{C} \pm 5^\circ\text{C}$,2seconds	(1)Over 95% of dipped part is covered with solder.	1	0
7	Pin strength test immunity test	(1) Weight $\phi 1$ pin : 1kg $\phi 2$ pin : 2kg (2) Bending angle:90 deg., total 180 deg. (3) 1 cycle	(1)No degradation of electric characteristics after test. (2)No broken or bent pin.	6	0
8	Static electricity immunity test	(1) Applied voltage $\pm 8\text{kV}$ (2) At rated input and load	(1)No protection circuit fail. (2)No output voltage drop with control circuit fail. (3)No any other function fail.	1	0